

**SEMICONDUCTOR DEVICES WITH SCALABLE TWO TRANSISTOR
MEMORY CELLS AND METHODS OF FABRICATING THE SAME**

Abstract of the Disclosure

Semiconductor devices having scalable two transistor memory cells, and
5 methods of fabricating the same, are disclosed. The semiconductor devices include a
semiconductor substrate having first, second and third isolation layers thereon. The
first and second isolation layers are spaced apart to define a first active region
therebetween, and the second and third isolation layers are likewise spaced apart to
form a second active region therebetween. A cell gate is provided on each active
10 region that includes a gate dielectric layer, a storage node, a multiple tunnel junction
barrier and a source layer that are sequentially stacked. The device also includes first
and second control lines that surround at least a portion of each sidewall of the cell
gates. A dielectric layer may be interposed between the sidewalls of the cell gates and
the control line that surrounds it. A data line connects to the cell gates.
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